7E4048

B. Tech. VII Semester (Main/Back) Examination, Nov-Dec - 2011
Electronics & Communication Engineering
7EC5 VLSI Design

Time: 3 Hours

Maximum Marks: 80

Min. Passing Marks: 24

Instructions to Candidates:

Attempt any five questions selecting one question from each unit. All questions carry equal marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly. Units of quantities used/calculated must be stated clearly.

Unit - I

- 1. a) Draw the MOS transistor circuit modal. Give the justification for all capacitance. Compare the different capacitance. Explain in detail for overloop capacitance.

 (12)
- b) Write and explain equation for V-I relationship of MOS transistor. (4)

SI AO or dynamic power dissipation

- 1. a) Draw and explain various step involved in n-well CMOS fabrication. (8)
 - b) Write comparative discussion of 'Twin-tub CMOS fabrication' and 'Silicon-on insulator' fabrication process. (8)

Unit - II

- 2. a) What are various second order effect? Explain how V-I characteristics modify with channel length modulation effect? Show it on V-I characteristics and in V-I relation. (10)
 - b) What is body effect? Write equations related to body effect threshold voltage.

(6)

(8)

2. a)	Calculate the V_{TO} NMOS, Given that $V_{SB} = 0$, $ni = 1.45 \times 10^{10}$,	$N_A = 10^{16}$	
	$N_D(gate) = 2 \times 10^{20}$. Gate electrode is polysilicon $tox = 500^{\circ} A$. (Oxide t	hickness	
	$Qox = 4 \times 10^{10}$), here Cox static charge.	(10)	
	7EC5 VLSI Design		
b)	Explain the influence of $\frac{\beta_n}{\beta_p}$ ratio on CMOS inverter DC transfer chara	cteristic.	
	Min. Passing Ma	(6)	
Instructions to Candidates: III - tinU			
2 0)			
3. a)	Why does NMOS transistor produces strong '0' and weak '1' whil transistor produces strong '1' and weak'0'?	(8)	
b)	Explain working of transmission gate. or pass transistor. What are ad and disadvantages of transmission gate.	vantages (8)	
OR			
3. a)	Design the following CMOS logic		
	Compare the different capacitance. Explain in detail for overloop cap (i) $\overline{3d + 3d + A} = Y$		
	Write and explain equation for V-I relationship of $\overline{AR} + \overline{AR} = Y$ (ii)	(8)	
6)	Explain and derive the expression for dynamic power dissipation of circuit.	of CMOS (8)	
	Draw and explain various step involved in n-well CMOS fabrication. VI - tinU		
	Write comparative discussion of 'Twin-tub CMOS fabrication' and 'S		
4. a)	Draw the stick diagram for		
	i) CMOS EX-OR Gate II - HIII		
	What are various second order effect? Explain how VXUM 1:5 [ii]	(10)	
(b)	Explain different types of layout design rules.	(6)	
	What is body effect? Write equations related to body effect threshold		
4. a)	Draw the physical layout for $X = \overline{ab + CD}$	(8)	
b)	Design layout for an n-diff wire connected to p-diff wire.	(8)	
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Unit - V

5.	a)	Write VHDL code for half adder by following modelling style.			
		i) Data flow			
		ii) Behavioral			
		iii) Structural (1	2)		
	b)	Write VHDL code for J-K flip-flop.	(4)		
	Instructions to Candidates: OR				
5.	a)	Write VHDL code for 3-bit counter.	(4)		
	b)	Write short notes on any Three of following. With references to the VHD	L.		
		i) Process statement			
		ii) Test-bench			
		iii) Types of delay			
		iv) Advantages and limitation of VHDL. (1	12)		
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